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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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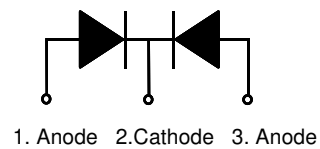
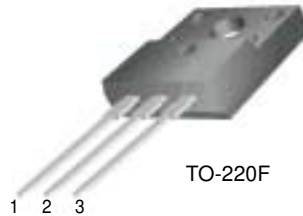
FFPF10U30DN

Features

- Ultrafast with soft recovery
- Low forward voltage

Applications

- Power switching circuits
- Output rectifiers
- Freewheeling diodes
- Switching mode power supply



ULTRA FAST RECOVERY POWER RECTIFIER

Absolute Maximum Ratings (per diode) $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{RRM}	Peak Repetitive Reverse Voltage	300	V
$I_{F(AV)}$	Average Rectified Forward Current @ $T_C = 100^\circ\text{C}$	10	A
I_{FSM}	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	100	A
T_J, T_{STG}	Operating Junction and Storage Temperature	- 65 to +150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	2.1	$^\circ\text{C}/\text{W}$

Electrical Characteristics (per diode) $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Units	
V_{FM}^*	Maximum Instantaneous Forward Voltage $I_F = 10\text{A}$	$T_C = 25^\circ\text{C}$	-	-	1.2	V
		$T_C = 100^\circ\text{C}$	-	-	1.1	
I_{RM}^*	Maximum Instantaneous Reverse Current @ rated V_R	$T_C = 25^\circ\text{C}$	-	-	10	μA
		$T_C = 100^\circ\text{C}$	-	-	100	
t_{rr}	Maximum Reverse Recovery Time	-	-	60	ns	
I_{rr}	Maximum Reverse Recovery Current	-	-	4.5	A	
Q_{rr}	Maximum Reverse Recovery Charge ($I_F = 10\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$)	-	-	135	nC	
W_{AVL}	Avalanche Energy	1.0	-	-	mJ	

* Pulse Test: Pulse Width=300 μs , Duty Cycle=2%

Typical Characteristics

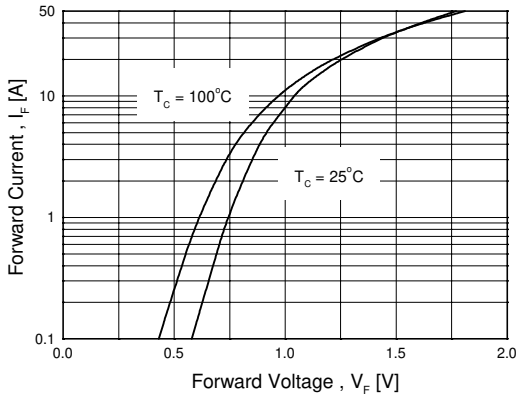


Figure 1. Typical Forward Voltage Drop vs. Forward Current

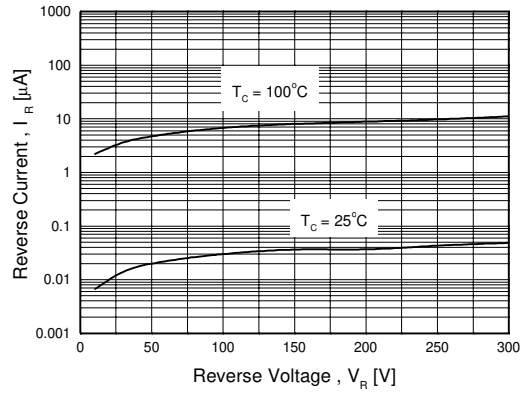


Figure 2. Typical Reverse Current vs. Reverse Voltage

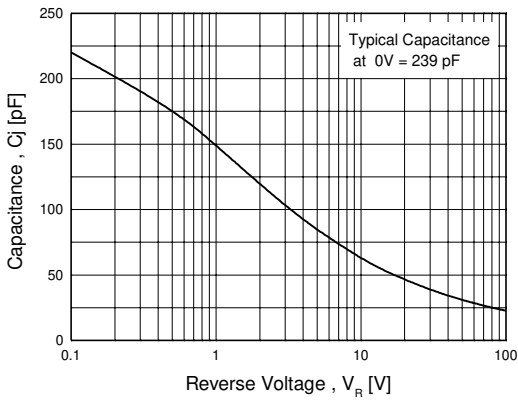


Figure 3. Typical Junction Capacitance

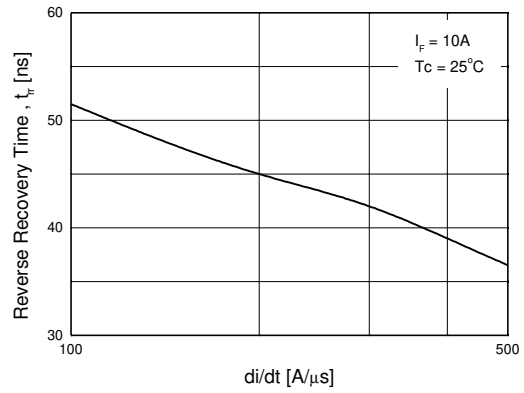


Figure 4. Typical Reverse Recovery Time vs. di/dt

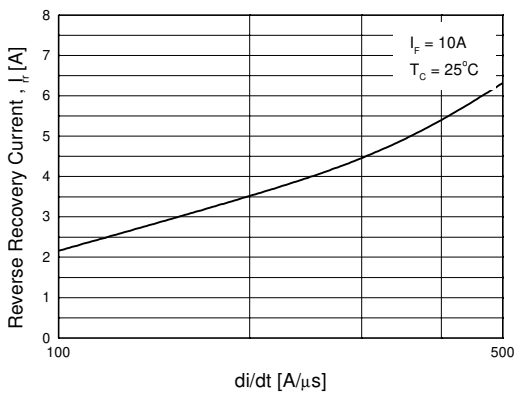


Figure 5. Typical Reverse Recovery Current vs. di/dt

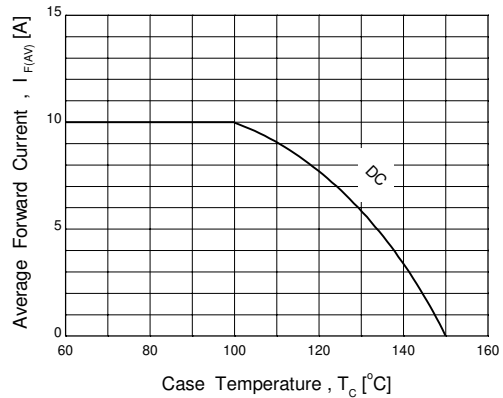
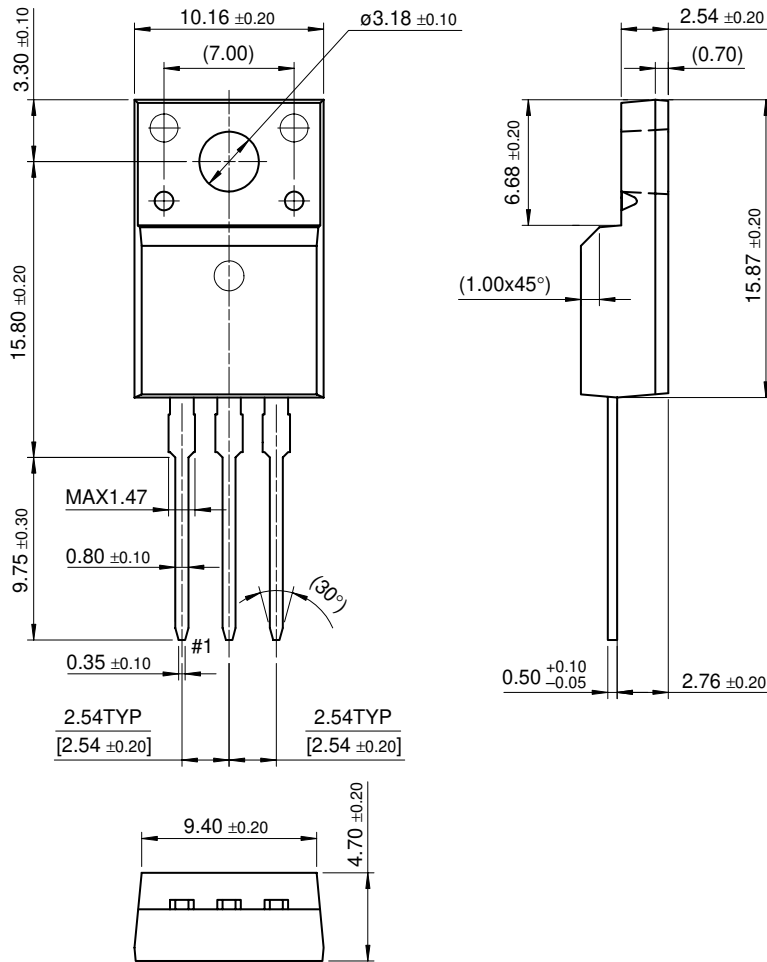


Figure 6. Forward Current Derating Curve

Package Dimensions

FFPF10U30DN

TO-220F



Dimensions in Millimeters

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